

RF Power Field Effect Transistors

N-Channel Enhancement-Mode Lateral MOSFETs

Designed primarily for large-signal output applications at 2450 MHz. Device is suitable for use in industrial, medical and scientific applications.

- Typical CW Performance at 2450 MHz, $V_{DD} = 28$ Volts, $I_{DQ} = 1200$ mA, $P_{out} = 140$ Watts
 Power Gain — 13.2 dB
 Drain Efficiency — 45%
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 2390 MHz, 140 Watts CW Output Power

Features

- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched for Ease of Use
- Qualified Up to a Maximum of 32 V_{DD} Operation
- Integrated ESD Protection
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.

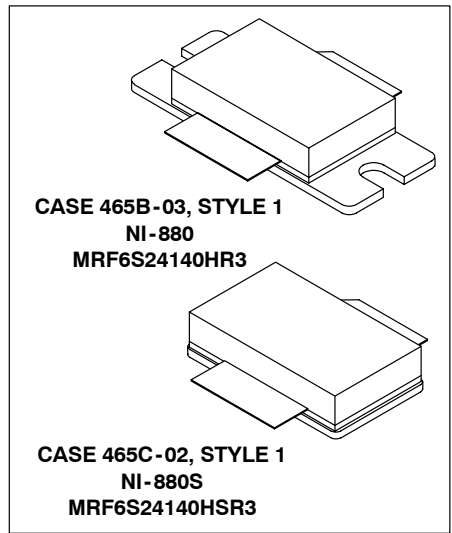
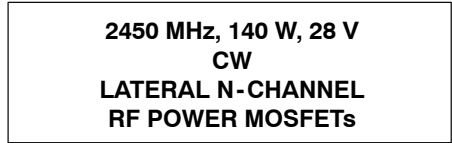
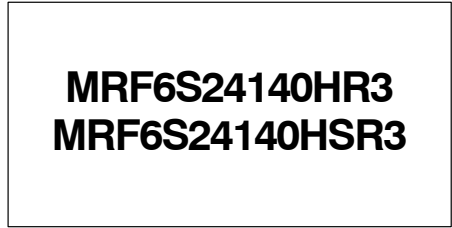


Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +68	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +12	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	150	°C
Operating Junction Temperature	T_J	200	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value (1,2)	Unit
Thermal Resistance, Junction to Case Case Temperature 82°C, 140 W CW Case Temperature 75°C, 28 W CW	$R_{\theta JC}$	0.29 0.33	°C/W

1. MTTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22-A114)	2 (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	IV (Minimum)

Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Off Characteristics

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 68\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	500	nAdc

On Characteristics

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 300\ \mu\text{Adc}$)	$V_{GS(th)}$	1	2	3	Vdc
Gate Quiescent Voltage ($V_{DS} = 28\text{ Vdc}$, $I_D = 1300\ \text{mAdc}$)	$V_{GS(Q)}$	2	2.8	4	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 3\text{ Adc}$)	$V_{DS(on)}$	0.1	0.21	0.3	Vdc

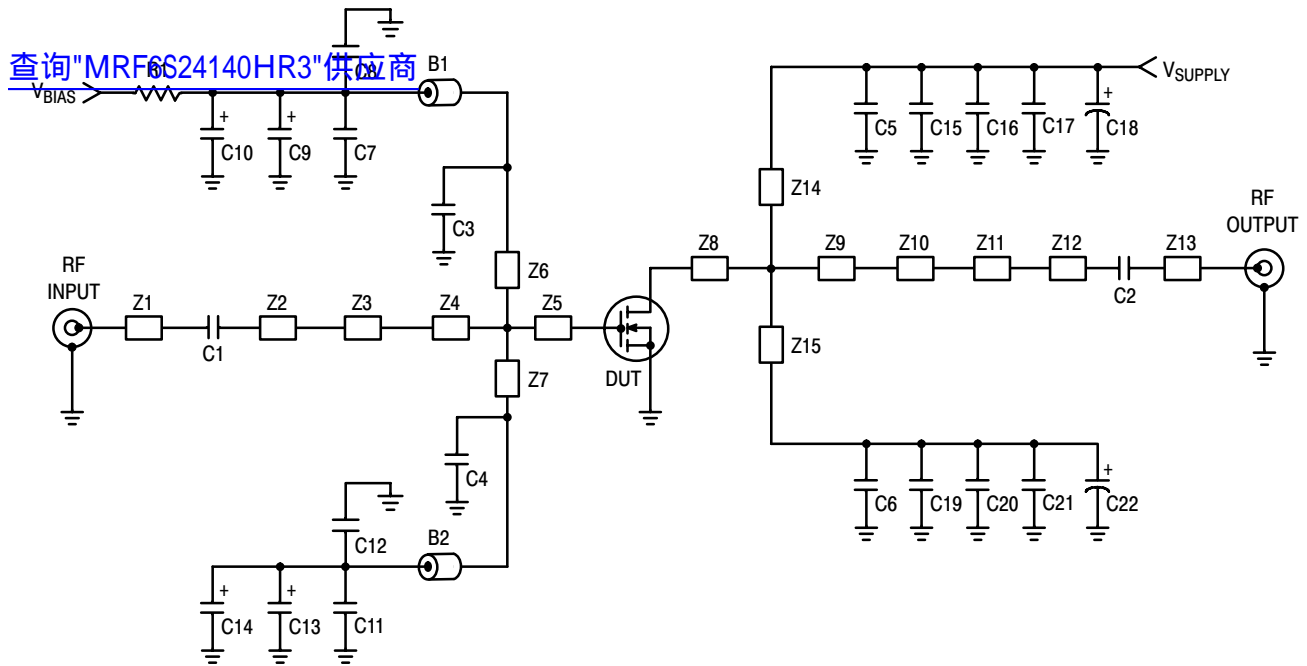
Dynamic Characteristics (1)

Reverse Transfer Capacitance ($V_{DS} = 28\text{ Vdc} \pm 30\ \text{mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	2	—	pF
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Functional Tests (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 1300\ \text{mA}$, $P_{out} = 28\text{ W Avg.}$, $f_1 = 2300\ \text{MHz}$, $f_2 = 2310\ \text{MHz}$ and $f_1 = 2390\ \text{MHz}$, $f_2 = 2400\ \text{MHz}$, 2-Carrier W-CDMA, 3.84 MHz Channel Bandwidth Carriers. ACPR measured in 3.84 MHz Channel Bandwidth @ $\pm 5\ \text{MHz}$ Offset. IM3 measured in 3.84 MHz Bandwidth @ $\pm 10\ \text{MHz}$ Offset. PAR = 8.5 dB @ 0.01% Probability on CCDF.

Power Gain	G_{ps}	13	15.2	17	dB
Drain Efficiency	η_D	23	25	—	%
Intermodulation Distortion	IM3	—	-37	-35	dBc
Adjacent Channel Power Ratio	ACPR	—	-40	-38	dBc
Input Return Loss	IRL	—	-15	—	dB

1. Part internally matched both on input and output.



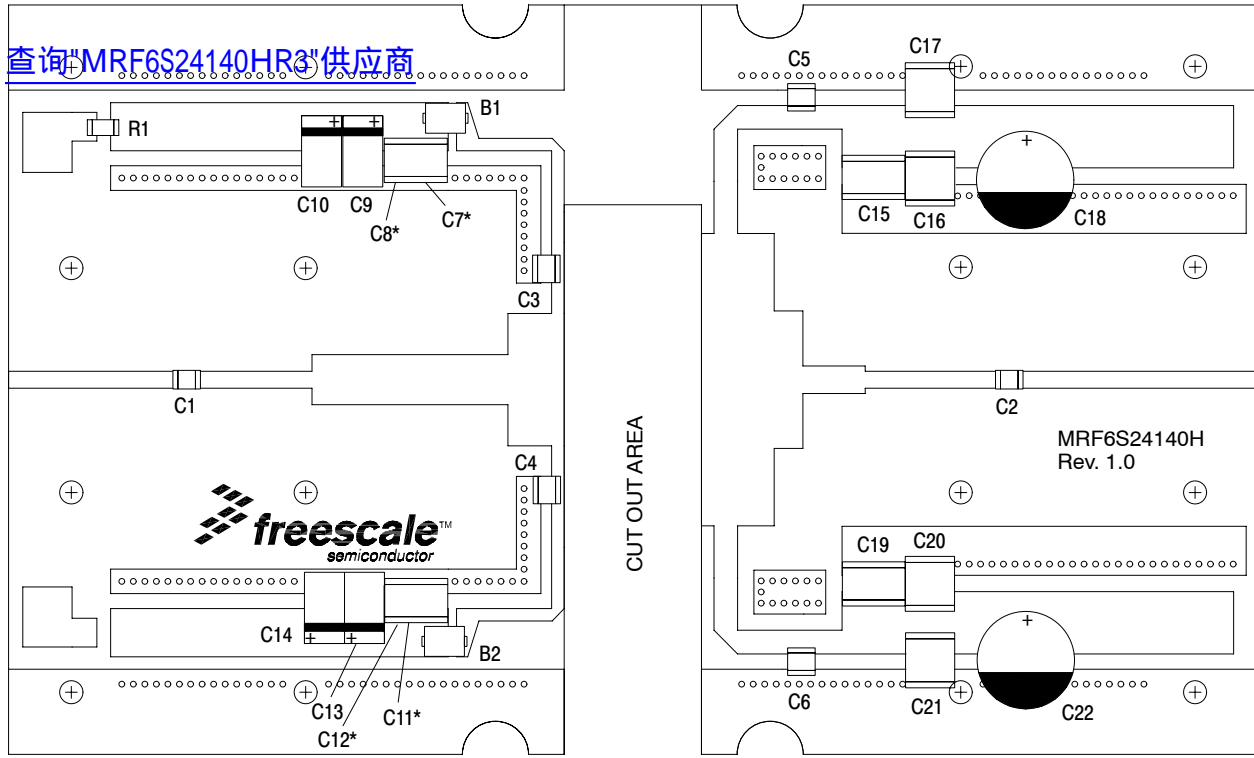
Z1	0.678" x 0.068" Microstrip	Z9	0.193" x 1.170" Microstrip
Z2	0.466" x 0.068" Microstrip	Z10	0.115" x 0.550" Microstrip
Z3	0.785" x 0.200" Microstrip	Z11	0.250" x 0.110" Microstrip
Z4	0.200" x 0.530" Microstrip	Z12	0.538" x 0.068" Microstrip
Z5	0.025" x 0.530" Microstrip	Z13	0.957" x 0.068" Microstrip
Z6, Z7	0.178" x 0.050" Microstrip	Z14, Z15	0.673" x 0.095" Microstrip
Z8	0.097" x 1.170" Microstrip	PCB	Arlon GX0300-55-22, 0.030", $\epsilon_r = 2.55$

Figure 1. MRF6S24140HR3(SR3) Test Circuit Schematic — 2450 MHz

Table 5. MRF6S24140HR3(SR3) Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
B1, B2	47 Ω , 100 MHz Short Ferrite Beads, Surface Mount	2743019447	Fair-Rite
C1, C2, C3, C4, C5, C6	5.6 pF Chip Capacitors	ATC600B5R6BT500XT	ATC
C7, C11	0.01 μ F, 100 V Chip Capacitors	C1825C103J1RAC	Kemet
C8, C12, C15, C19	2.2 μ F, 50 V Chip Capacitors	C1825C225J5RAC	Kemet
C9, C13	22 μ F, 25 V Tantalum Capacitors	T491D226M025AT	Kemet
C10, C14	47 μ F, 16 V Tantalum Capacitors	T491D476K016AC	Kemet
C16, C17, C20, C21	10 μ F, 50 V Chip Capacitors	GRM55DR61H106KA88B	Murata
C18, C22	220 μ F, 50 V Electrolytic Capacitors	EMVY50VC221MJ10TP	United Chemi-Con
R1	240 Ω , 1/4 W Chip Resistor	CRC1206240RFKTA	Vishay

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* Stacked

Figure 2. MRF6S24140HR3(SR3) Test Circuit Component Layout — 2450 MHz

TYPICAL CHARACTERISTICS — 2450 MHz

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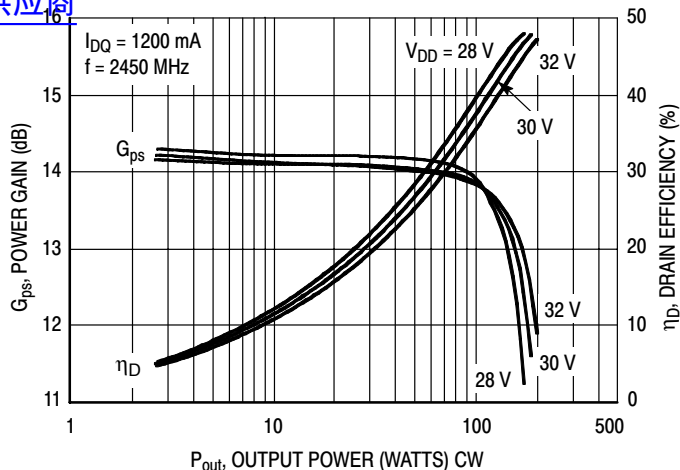


Figure 3. Power Gain and Drain Efficiency versus CW Output Power as a Function of V_{DD}

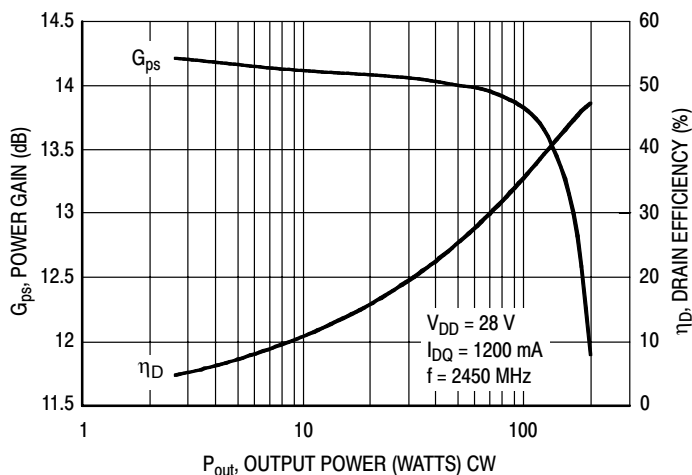


Figure 4. Power Gain and Drain Efficiency versus CW Output Power

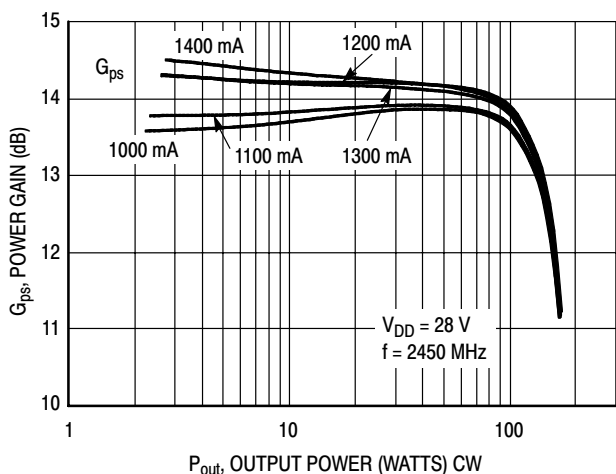
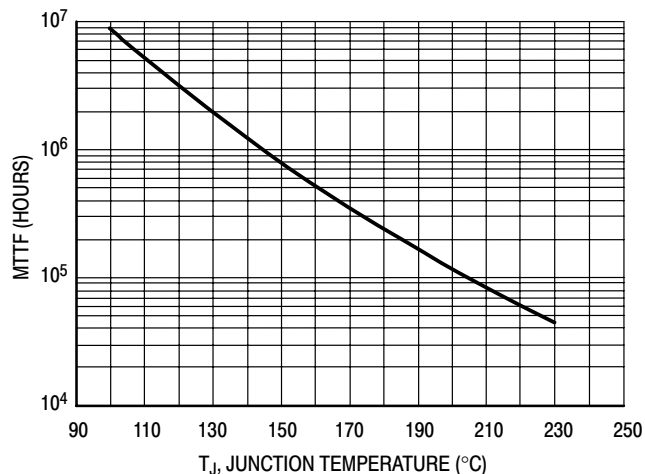


Figure 5. Power Gain and Drain Efficiency versus CW Output Power as a Function of Total I_{DQ}

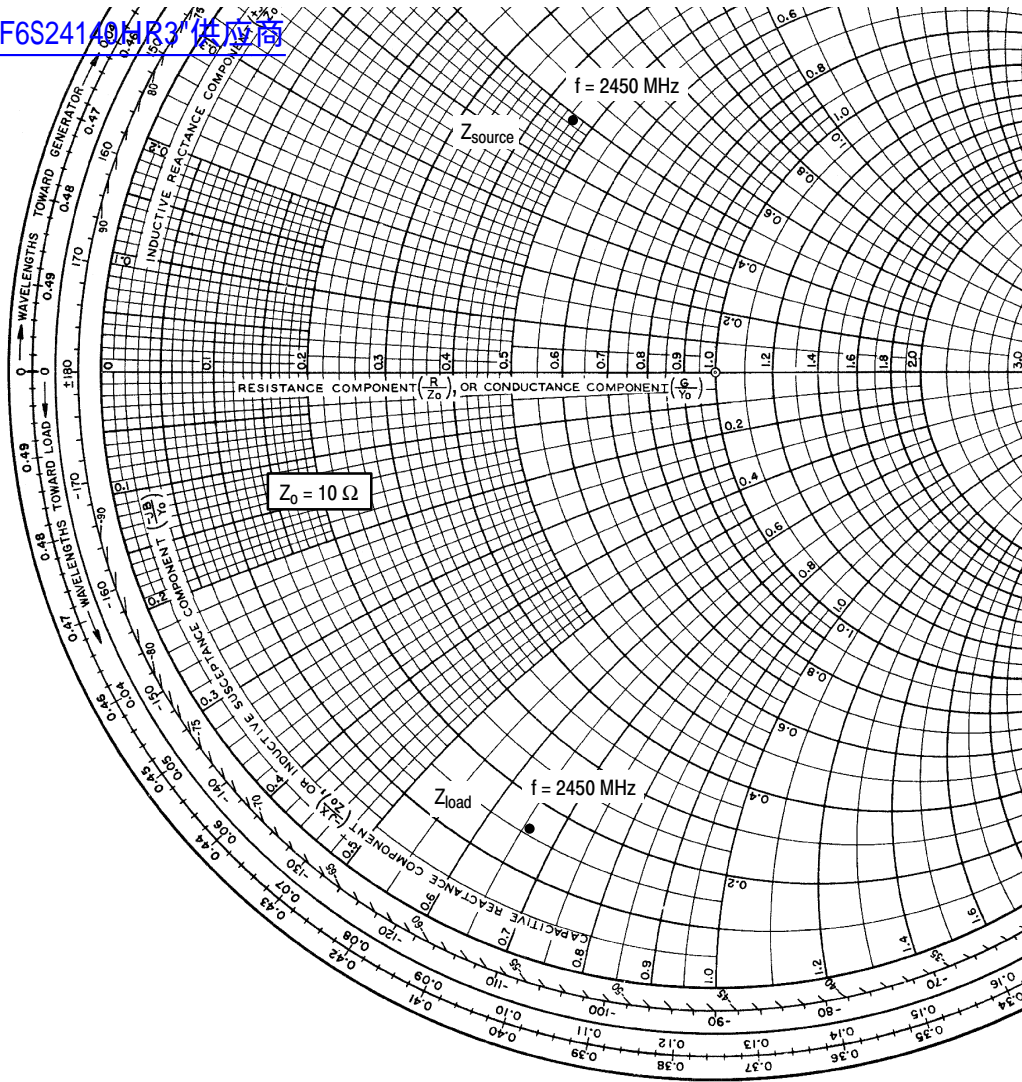


This above graph displays calculated MTTF in hours when the device is operated at $V_{DD} = 28$ Vdc, $P_{out} = 140$ W CW, and $\eta_D = 45\%$.

MTTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.

Figure 6. MTTF versus Junction Temperature

MRF6S24140HR3 MRF6S24140HSR3



$V_{DD} = 28 \text{ Vdc}$, $I_{DQ} = 1200 \text{ mA}$, $P_{out} = 140 \text{ W CW}$

f MHz	Z _{source} Ω	Z _{load} Ω
2450	4.55 + j4.9	1.64 - j6.57

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

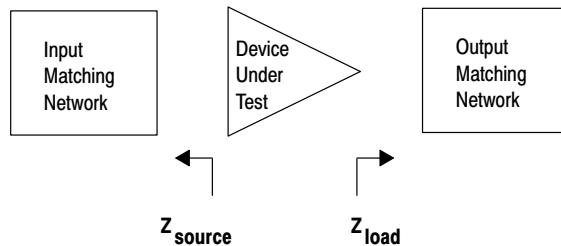
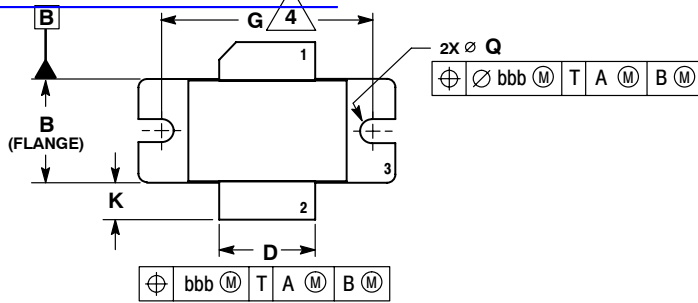


Figure 7. Series Equivalent Source and Load Impedance

PACKAGE DIMENSIONS

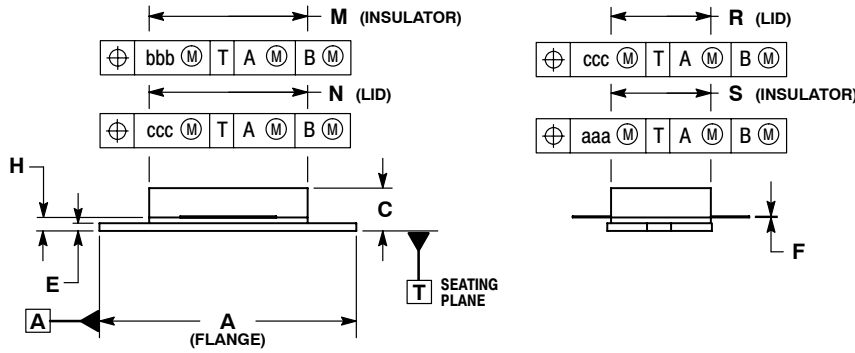
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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
4. RECOMMENDED BOLT CENTER DIMENSION OF 1.16 (29.57) BASED ON M3 SCREW.

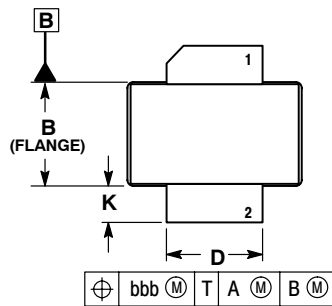
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.535	0.545	13.6	13.8
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.175	0.205	4.44	5.21
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
Q	\varnothing 0.118	\varnothing 0.138	\varnothing 3.00	\varnothing 3.51
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	



CASE 465B-03
ISSUE D
NI-880
MRF6S24140HR3

STYLE 1:

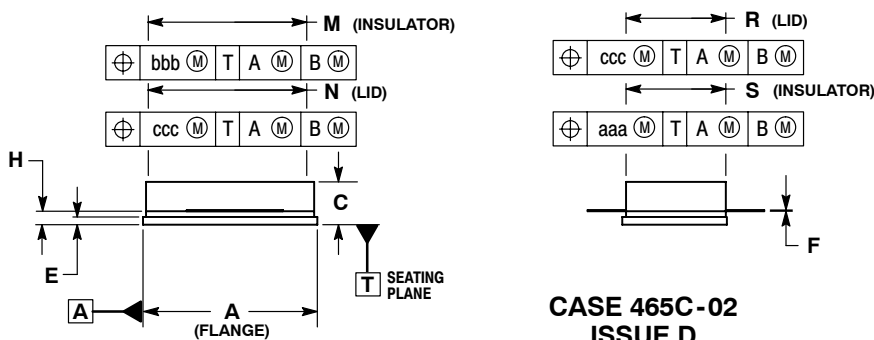
1. DRAIN
2. GATE
3. SOURCE



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.905	0.915	22.99	23.24
B	0.535	0.545	13.60	13.80
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	



CASE 465C-02
ISSUE D
NI-880S
MRF6S24140HSR3

STYLE 1:

1. DRAIN
2. GATE
3. SOURCE

MRF6S24140HR3 MRF6S24140HSR3

PRODUCT DOCUMENTATION

[查询"MRF6S24140HR3"供应商](#)
Refer to the following documents to aid your design process.

Application Notes

- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	Mar. 2007	<ul style="list-style-type: none">• Initial Release of Data Sheet

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